

Environmental testing - Part 2-58: Tests - Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

See Eesti standard EVS-EN 60068-2-58:2015 sisaldab Euroopa standardi EN 60068-2-58:2015 ingliskeelset teksti.	This Estonian standard EVS-EN 60068-2-58:2015 consists of the English text of the European standard EN 60068-2-58:2015.
Standard on jõustunud sellekohase teate avaldamisega EVS Teatajas	This standard has been endorsed with a notification published in the official bulletin of the Estonian Centre for Standardisation.
Euroopa standardimisorganisatsioonid on teinud Euroopa standardi rahvuslikele liikmetele kättesaadavaks 08.05.2015.	Date of Availability of the European standard is 08.05.2015.
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English Version

Environmental testing - Part 2-58: Tests - Test Td: Test methods
for solderability, resistance to dissolution of metallization and to
soldering heat of surface mounting devices (SMD)
(IEC 60068-2-58:2015)

Essais d'environnement - Partie 2-58: Essais - Essai Td:
Méthodes d'essai de la soudabilité, résistance de la
métallisation à la dissolution et résistance à la chaleur de
brasage des composants pour montage en surface (CMS)
(IEC 60068-2-58:2015)

Umweltprüfungen - Teil 2-58: Prüfungen - Prüfung Td:
Prüfverfahren für Lötbarkeit, Widerstandsfähigkeit
gegenüber Auflösen der Metallisierung und
Lötwärmebeständigkeit bei oberflächenmontierbaren
Bauelementen (SMD)
(IEC 60068-2-58:2015)

This European Standard was approved by CENELEC on 2015-05-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

Foreword

The text of document 91/1222/FDIS, future edition 4 of IEC 60068-2-58, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60068-2-58:2015.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2016-02-01
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2018-05-01

This document supersedes EN 60068-2-58:2004.

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Endorsement notice

The text of the International Standard IEC 60068-2-58:2015 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60068-2-54	NOTE	Harmonized as EN 60068-2-54.
IEC 60068-2-69	NOTE	Harmonized as EN 60068-2-69.
IEC 60749-20	NOTE	Harmonized as EN 60749-20.
IEC 61760-3	NOTE	Harmonized as EN 61760-3.
IEC 61760-4	NOTE	Harmonized as EN 61760-4 ¹⁾ .

1) To be published.

Annex ZA
(normative)

**Normative references to international publications
with their corresponding European publications**

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60068-1	-	Environmental testing - Part 1: General and guidance	EN 60068-1	-
IEC 60068-2-20	2008	Environmental testing - Part 2-20: Tests - Test T: Test methods for solderability and resistance to soldering heat of devices with leads	EN 60068-2-20	2008
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	EN 60194	-
IEC 61190-1-1	-	Attachment materials for electronic assembly - Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly	EN 61190-1-1	-
IEC 61190-1-2	2014	Attachment materials for electronic assembly - Part 1-2: Requirements for soldering pastes for high-quality interconnects in electronics assembly	EN 61190-1-2	2014
IEC 61190-1-3 + A1	2007 2010	Attachment materials for electronic assembly - Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications	EN 61190-1-3 + A1	2007 2010
IEC 61191-2	-	Printed board assemblies - Part 2: Sectional specification - Requirements for surface mount soldered assemblies	EN 61191-2	-

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61249-2-22	-	Materials for printed boards and other interconnecting structures - Part 2-22: Reinforced base materials, clad and unclad - Modified non-halogenated epoxide woven E-glass laminated sheets of defined flammability (vertical burning test), copper-clad	EN 61249-2-22	-
IEC 61249-2-35	-	Materials for printed boards and other interconnecting structures - Part 2-35: Reinforced base materials, clad and unclad - Modified epoxide woven E-glass laminate sheets of defined flammability (vertical burning test), copper-clad for lead-free assembly	EN 61249-2-35	-
IEC 61760-1	-	Surface mounting technology - Part 1: Standard method for the specification of surface mounting components (SMDs)	EN 61760-1	-
ISO 9454-2	1998	Soft soldering fluxes - Classification and requirements - Part 2: Performance requirements	EN ISO 9454-2	2000

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